

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE $\bar{S}$ - $\bar{R}$ LATCHES

SDLS093 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs

- Dependable Texas Instruments Quality and Reliability

description

The '279 offers 4 basic $\bar{S}$ - $\bar{R}$ flip-flop latches in one 16-pin, 300-mil package. Under conventional operation, the $\bar{S}$ - $\bar{R}$ inputs are normally held high. When the $\bar{S}$ input is pulsed low, the Q output will be set high. When $\bar{R}$ is pulsed low, the Q output will be reset low. Normally, the $\bar{S}$ - $\bar{R}$ inputs should not be taken low simultaneously. The Q output will be unpredictable in this condition.

FUNCTION TABLE
(each latch)

INPUTS		OUTPUT
$\bar{S}$ [†]	$\bar{R}$	Q
H	H	Q ₀
L	H	H
H	L	L
L	L	H [‡]

H = high level L = low level

[†]For latches with double S inputs:

Q₀ = the level of Q before the indicated input conditions were established.

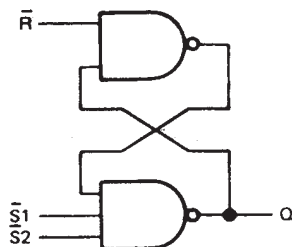
[‡]This configuration is nonstable; that is, it may not persist when the $\bar{S}$ and $\bar{R}$ inputs return to their inactive (high) level.

H = both $\bar{S}$ inputs high

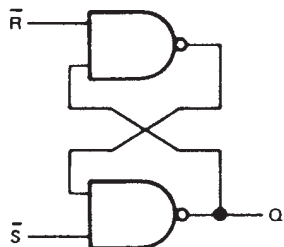
L = one or both $\bar{S}$ inputs low

logic diagram (positive logic)

(latches 1 and 3)



(latches 2 and 4)

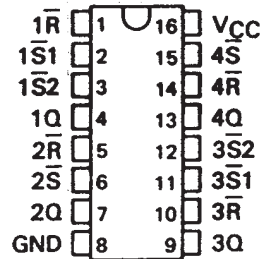


SN54279, SN54LS279A . . . J OR W PACKAGE

SN74279 . . . N PACKAGE

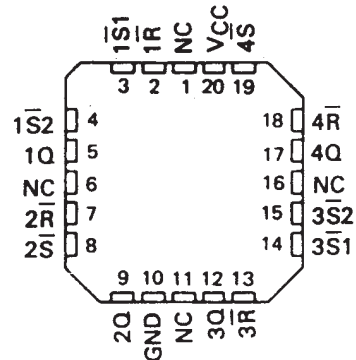
SN74LS279A . . . D OR N PACKAGE

(TOP VIEW)



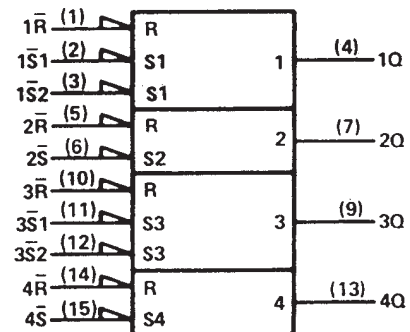
SN54LS279A . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

logic symbol[§]



[§]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

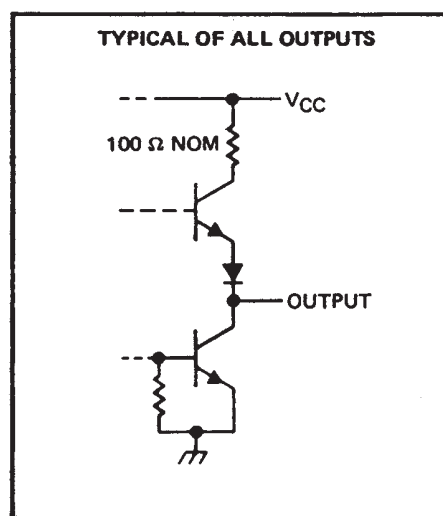
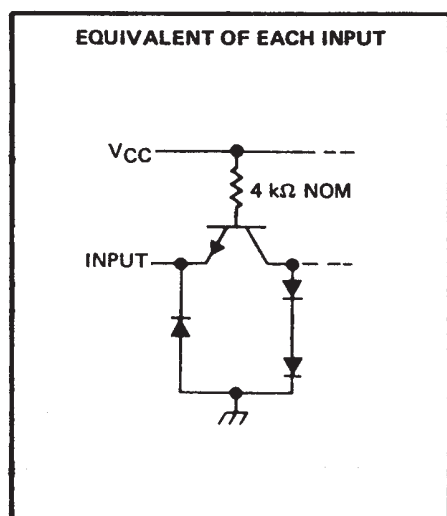
Pin numbers shown are for D, J, N, and W packages.

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE S-R LATCHES

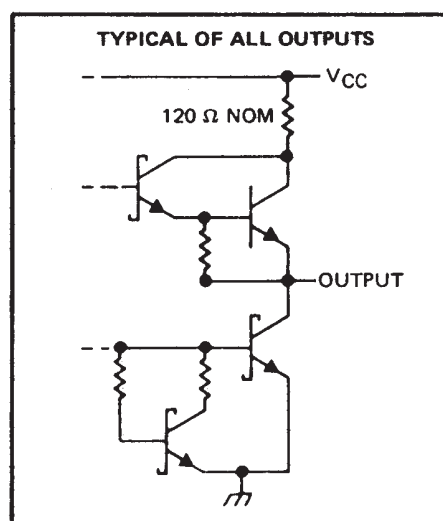
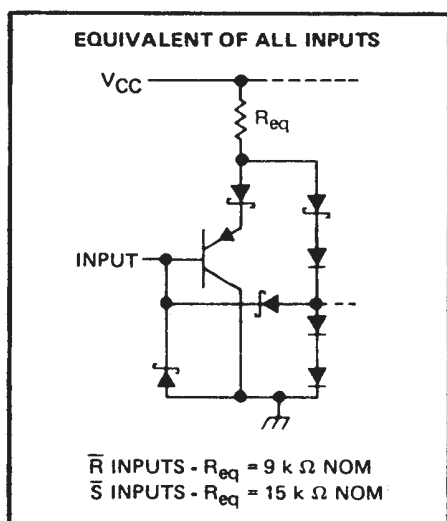
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schematics of inputs and outputs

'279 CIRCUITS



'LS279A CIRCUITS



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage: '279	5.5 V
' LS279A	7 V
Operating free-air temperature range: SN54' TYPES	- 55° C to 125° C
SN74' TYPES	0° C to 70° C
Storage temperature range	- 65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE S-R LATCHES

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recommended operating conditions

	SN54279			SN74279			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
I _{OH} High-level output current			– 0.8			– 0.8	mA
I _{OL} Low-level output current			16			16	mA
t _w Pulse duration, low	20			20			ns
T _A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54279			SN74279			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = – 12 mA			– 1.5			– 1.5	V
V _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = – 0.8 mA	2.4	3.4		2.4	3.4		V
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I _I	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V			40			40	µA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			– 1.6			– 1.6	mA
I _{OS} §	V _{CC} = MAX	– 18		– 55	– 18		– 57	mA
I _{CC}	V _{CC} = MAX, See Note 2		18	30		18	30	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	S	Q	R _L = 400 Ω, C _L = 15 pF	12	22	ns	
t _{PHL}				9	15		
t _{PHL}	R	Q		15	27	ns	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE S-R LATCHES

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recommended operating conditions

	SN54LS279A			SN74LS279A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.7			0.8	V
I _{OH} High-level output current			– 0.4			– 0.4	mA
I _{OL} Low-level output current			4			8	mA
t _w Pulse duration, low	20			20			ns
T _A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS279A			SN74LS279A			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = – 18 mA			– 1.5			– 1.5	V
V _{OH}	V _{CC} = MIN, V _{IL} = MAX, I _{OH} = – 0.4 mA	2.5	3.4		2.7	3.4		V
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 8 mA					0.25	0.5	
I _I	V _{CC} = MAX, V _I = 7 V			0.1			0.1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.7 V			20			20	μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			– 0.2			– 0.2	mA
I _{OS} §	V _{CC} = MAX	– 20		– 100	– 20		– 100	mA
I _{CC}	V _{CC} = MAX, See note 2		3.8	7		3.8	7	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should be less than one second.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	$\bar{S}$	Q	R _L = 2 kΩ, C _L = 15 pF		12	22	ns
t _{PHL}					13	21	
t _{PHL}	$\bar{R}$	Q			15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
76018012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
7601801EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7601801EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7601801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7601801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74279N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74279N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74279N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74279N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS279AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS279AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS279ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS279ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS279ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54279J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54279W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54279W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54LS279AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS279AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS279AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS279AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS279AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

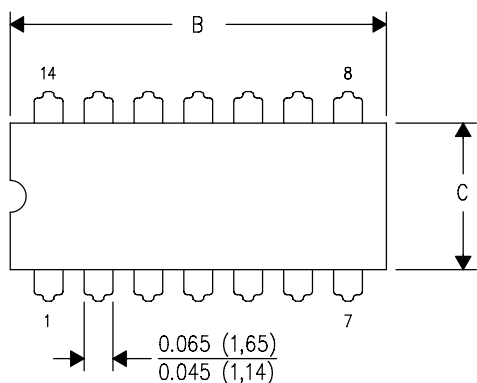
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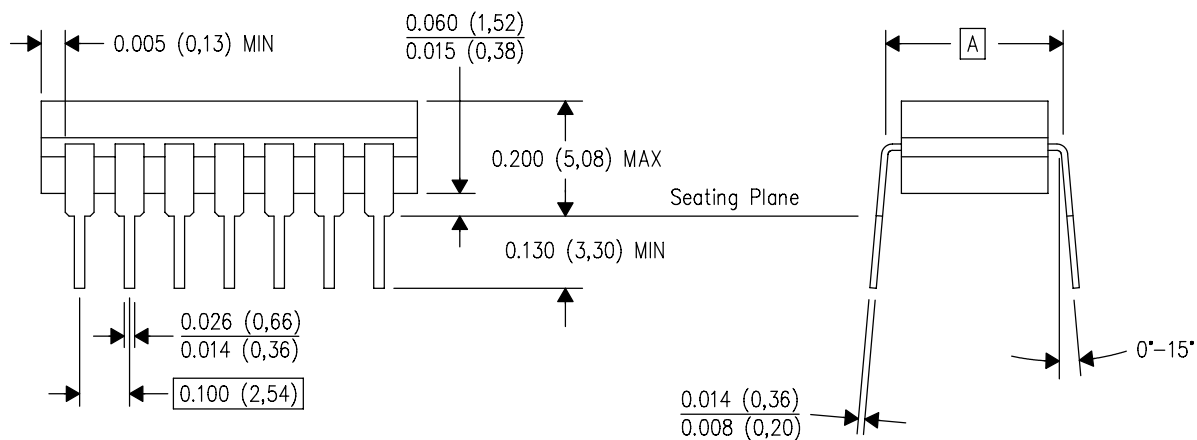
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

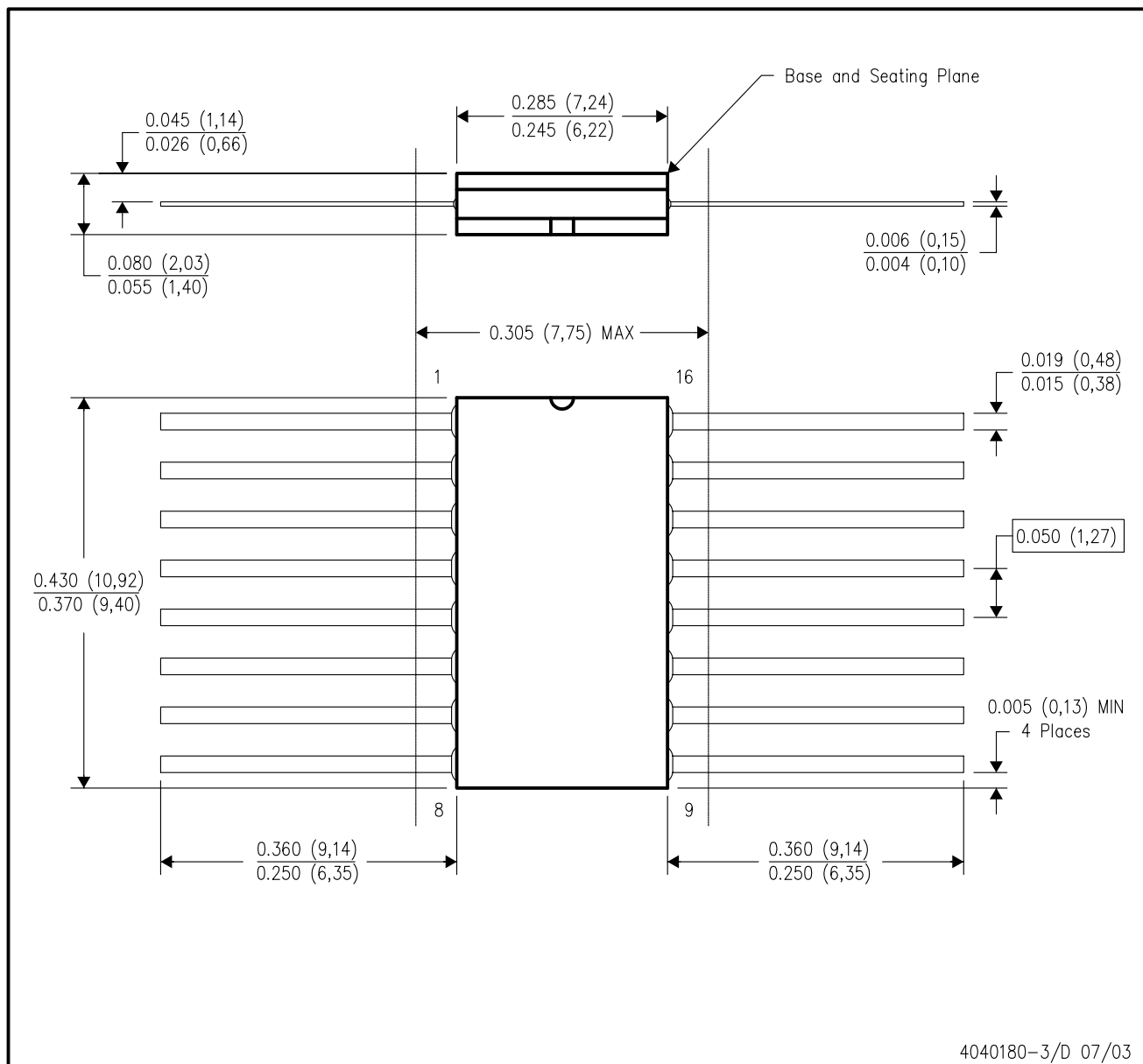


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

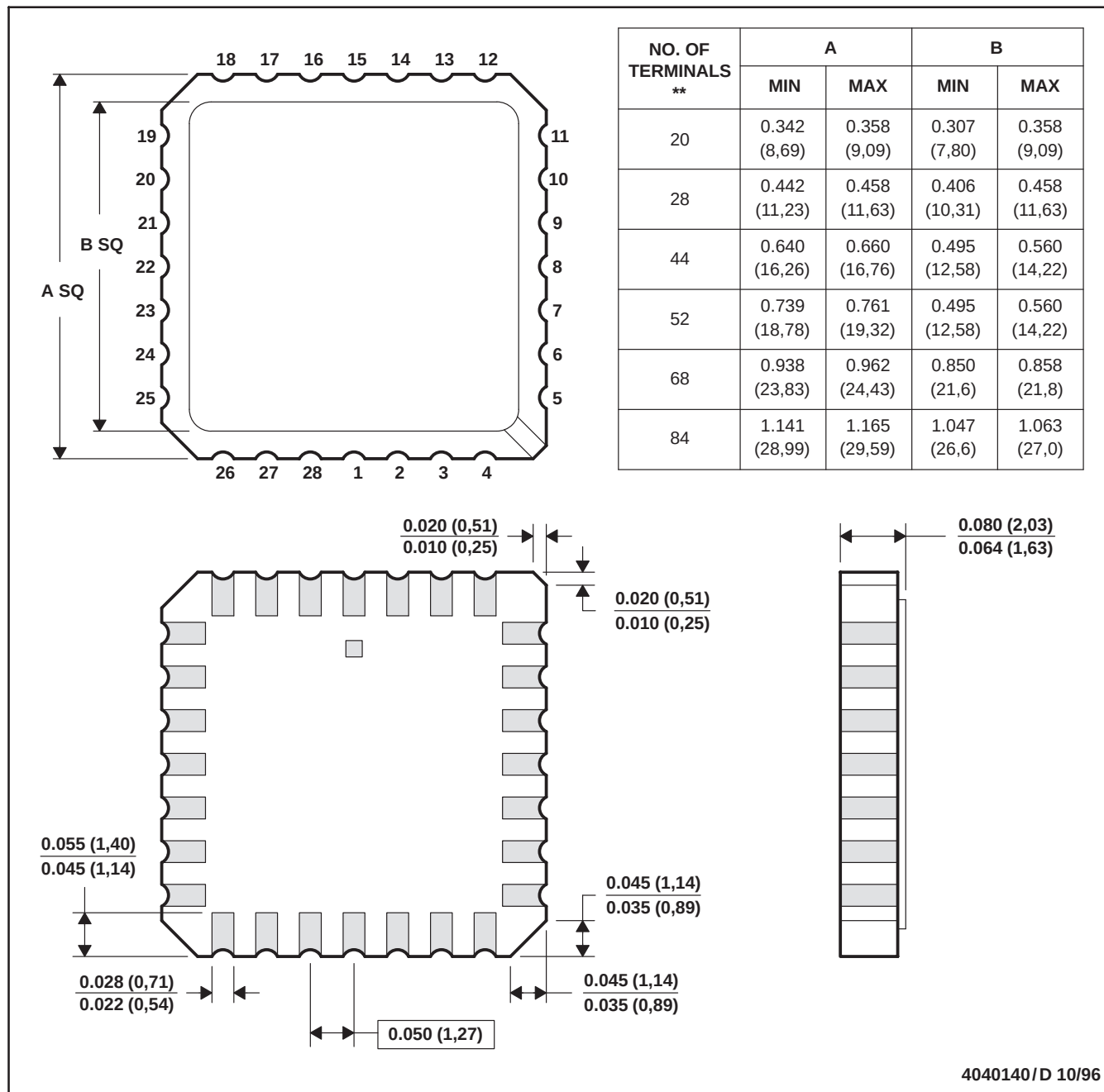


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

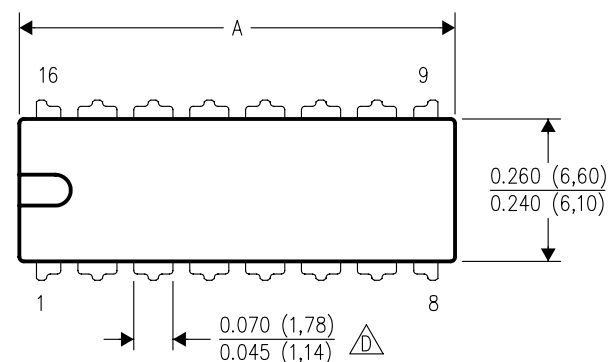


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

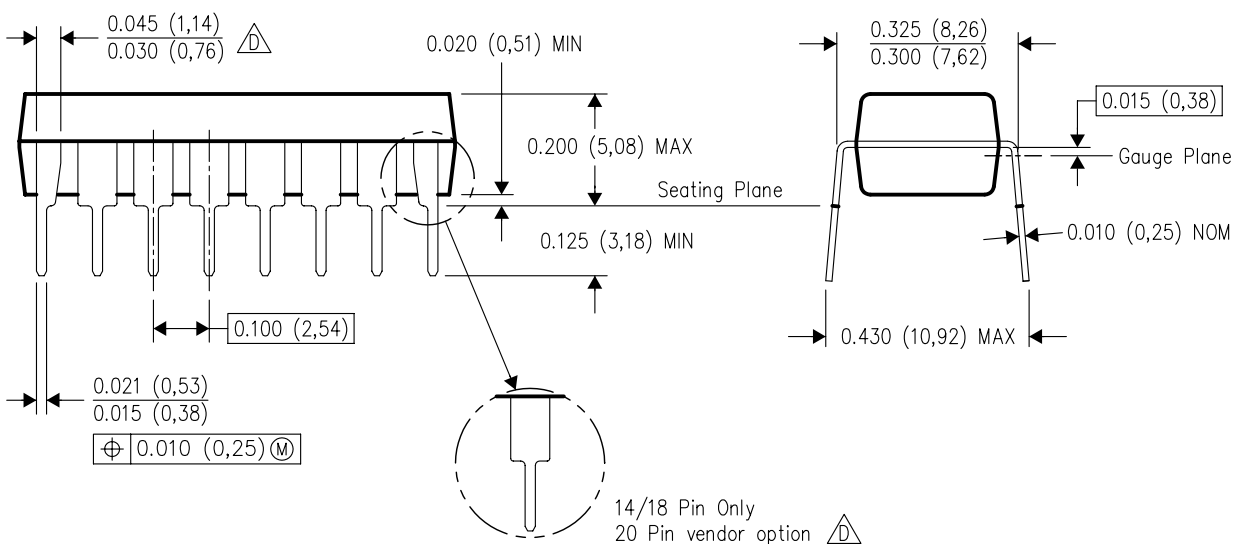
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



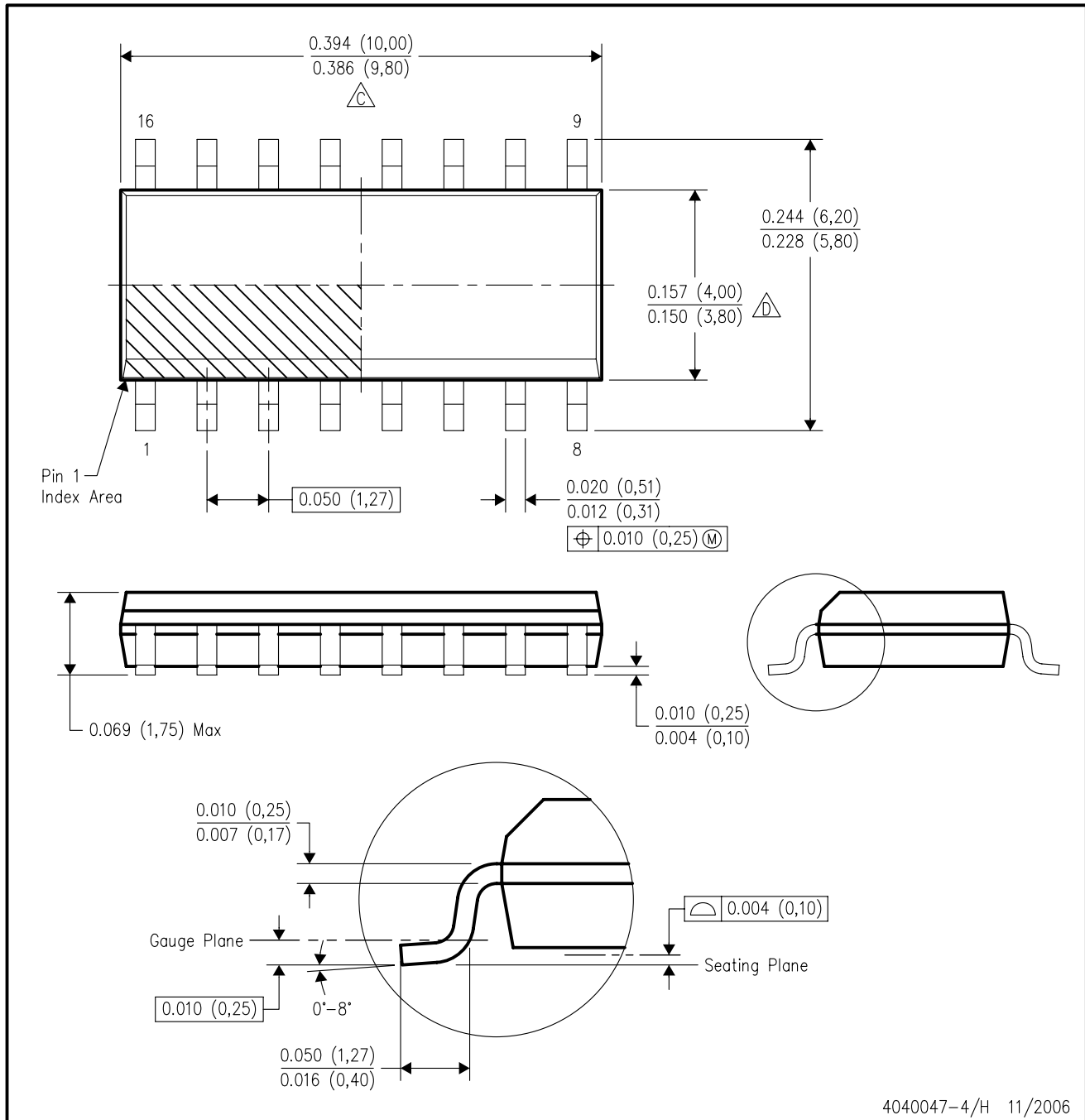
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

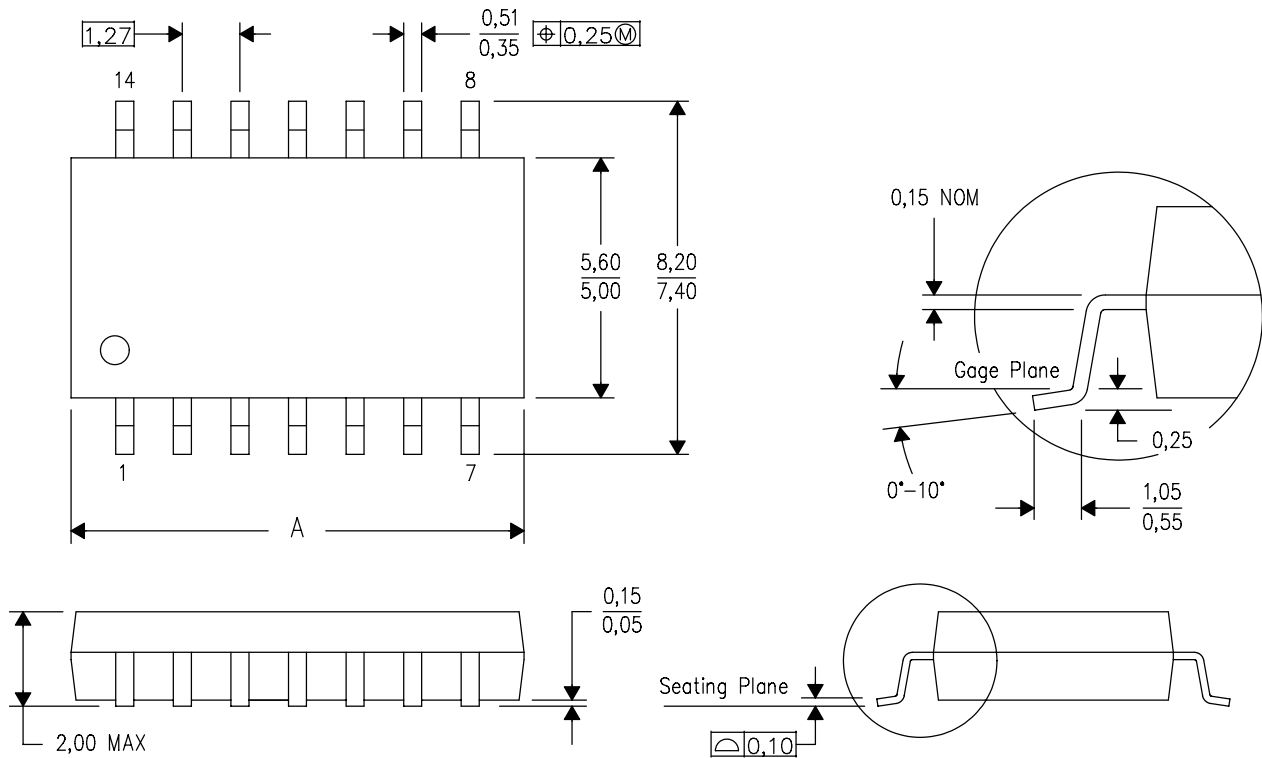
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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